

General Description

The AO4703 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. A Schottky diode is provided to facilitate the implementation of non-synchronous DC-DC converters. *Standard Product AO4703 is Pb-free (meets ROHS & Sony 259 specifications). AO4703L is a Green Product ordering option. AO4703 and AO4703L are electrically identical.*

Features

$$V_{DS} (V) = -30V$$

$$I_D = -12A (V_{GS} = -20V)$$

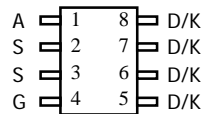
$$R_{DS(ON)} < 14m\Omega (V_{GS} = -20V)$$

$$R_{DS(ON)} < 15m\Omega (V_{GS} = -10V)$$

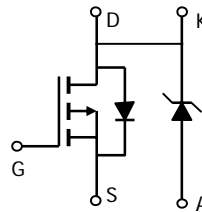


SCHOTTKY

$$V_{DS} (V) = 30V, I_F = 3A, V_F = 0.5V@1A$$



SOIC-8



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	MOSFET	Schottky	Units
Drain-Source Voltage	V_{DS}	-30		V
Gate-Source Voltage	V_{GS}	± 25		V
Continuous Drain Current ^A	I_D	$T_A=25^\circ C$	-12	A
		$T_A=70^\circ C$	-10	
Pulsed Drain Current ^B	I_{DM}	-60		
Schottky reverse voltage	V_{KA}		30	V
Continuous Forward Current ^A	I_F	$T_A=25^\circ C$	4.4	A
		$T_A=70^\circ C$	3.2	
Pulsed Forward Current ^B	I_{FM}		30	
Power Dissipation	P_D	$T_A=25^\circ C$	3	W
		$T_A=70^\circ C$	2.1	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	-55 to 150	$^\circ C$

Parameter: Thermal Characteristics MOSFET		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$t \leq 10s$	$R_{\theta JA}$	28	40	$^\circ C/W$
Maximum Junction-to-Ambient ^A	Steady-State		54	75	
Maximum Junction-to-Lead ^C	Steady-State	$R_{\theta JL}$	21	30	
Thermal Characteristics Schottky					
Maximum Junction-to-Ambient ^A	$t \leq 10s$	$R_{\theta JA}$		40	$^\circ C/W$
Maximum Junction-to-Ambient ^A	Steady-State			75	
Maximum Junction-to-Lead ^C	Steady-State	$R_{\theta JL}$			

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}$, $V_{GS}=0\text{V}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-24\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-1 -5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 25\text{V}$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-1.7	-2.5	-3	V
$I_{D(ON)}$	On state drain current	$V_{GS}=-10\text{V}$, $V_{DS}=-5\text{V}$	60			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-10\text{A}$ $T_J=125^\circ\text{C}$		12 16	15 20	$\text{m}\Omega$
		$V_{GS}=-20\text{V}$, $I_D=-10\text{A}$		11	14	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-10\text{A}$		25		$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}$, $I_D=-10\text{A}$		26		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}$, $V_{GS}=0\text{V}$		-0.72	-1	V
I_S	Maximum Body-Diode Continuous Current				-4.2	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance			2076		pF
C_{oss}	Output Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=-15\text{V}$, $f=1\text{MHz}$		503		pF
C_{rss}	Reverse Transfer Capacitance			302		pF
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$		2		Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge			37.2		nC
Q_{gs}	Gate Source Charge	$V_{GS}=-10\text{V}$, $V_{DS}=-15\text{V}$, $I_D=-12\text{A}$		7		nC
Q_{gd}	Gate Drain Charge			10.4		nC
$t_{D(on)}$	Turn-On Delay Time			12.4		ns
t_r	Turn-On Rise Time	$V_{GS}=-10\text{V}$, $V_{DS}=-15\text{V}$, $R_L=1.25\Omega$		8.2		ns
$t_{D(off)}$	Turn-Off Delay Time	$R_{GEN}=3\Omega$		25.6		ns
t_f	Turn-Off Fall Time			12		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-12\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		33		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-12\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		23		nC
SCHOTTKY PARAMETERS						
V_F	Forward Voltage Drop	$I_F=1.0\text{A}$		0.45	0.5	V
I_{rm}	Maximum reverse leakage current	$V_R=30\text{V}$		0.007	0.05	mA
		$V_R=30\text{V}$, $T_J=125^\circ\text{C}$		3.2	10	
		$V_R=30\text{V}$, $T_J=150^\circ\text{C}$		12	20	
C_T	Junction Capacitance	$V_R=15\text{V}$		37		pF

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D: The static characteristics in Figures 1 to 6,12,14 are obtained using 80 μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

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P-CHANNEL: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

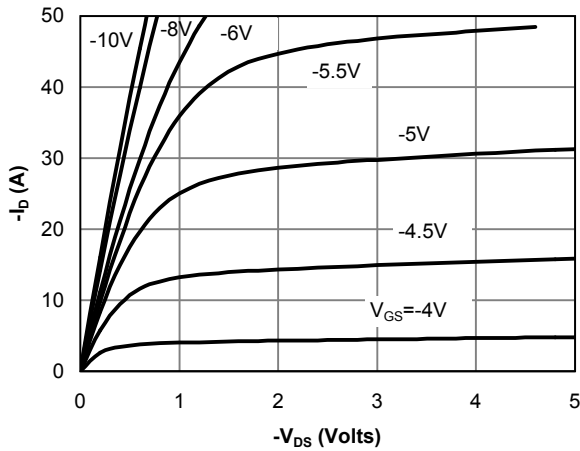


Fig 1: On-Region Characteristics

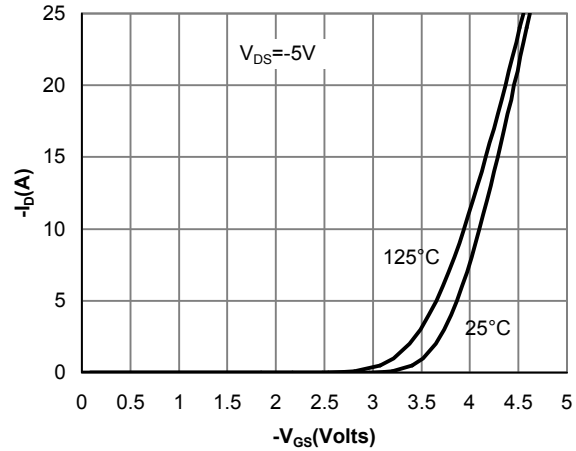


Figure 2: Transfer Characteristics

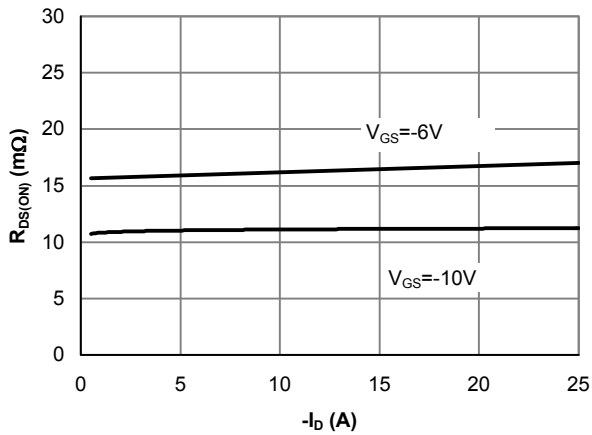


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

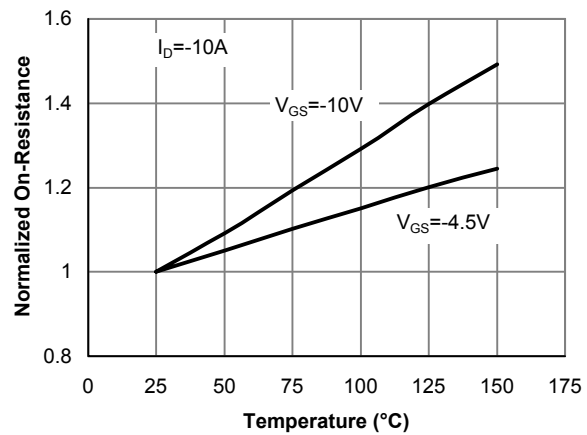


Figure 4: On-Resistance vs. Junction Temperature

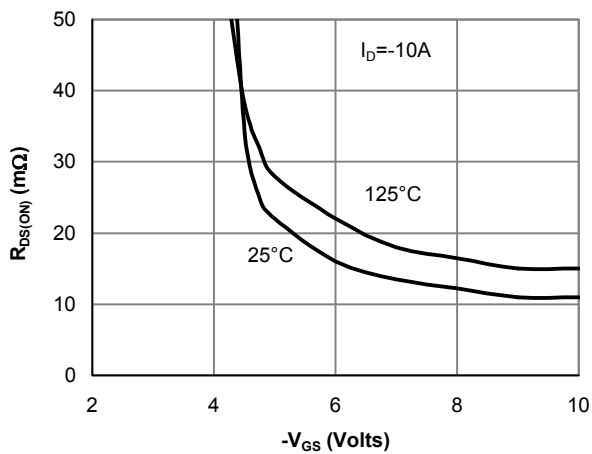


Figure 5: On-Resistance vs. Gate-Source Voltage

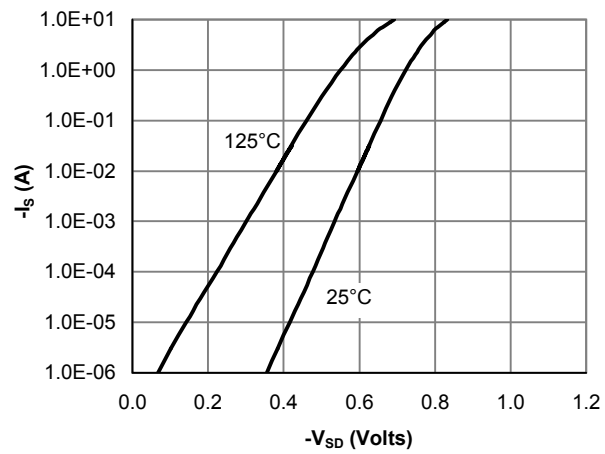


Figure 6: Body-Diode Characteristics

P-CHANNEL: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

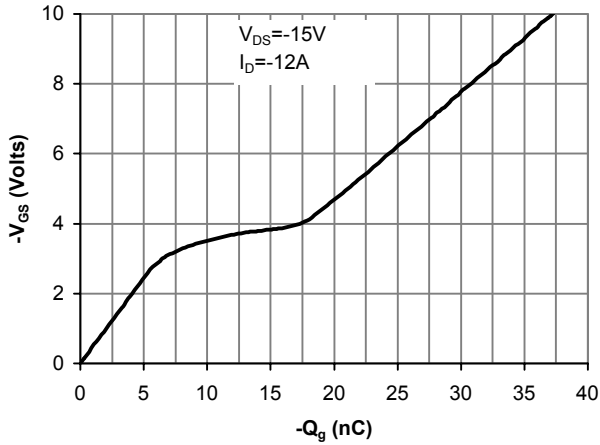


Figure 7: Gate-Charge Characteristics

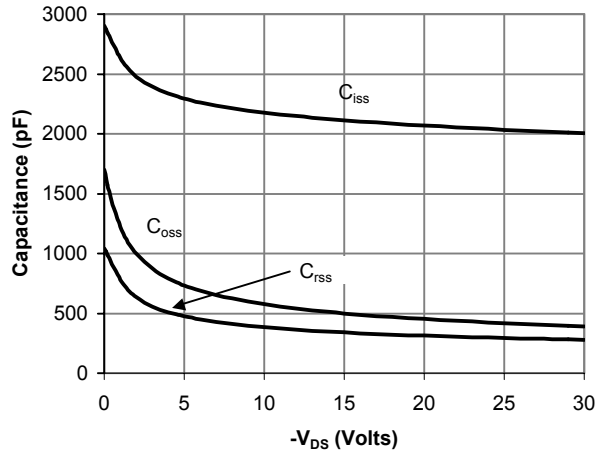


Figure 8: Capacitance Characteristics

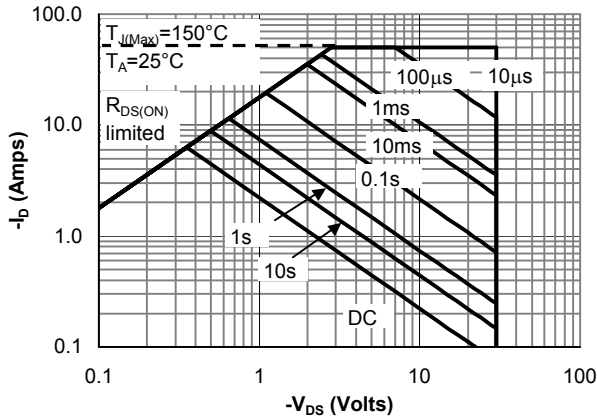


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

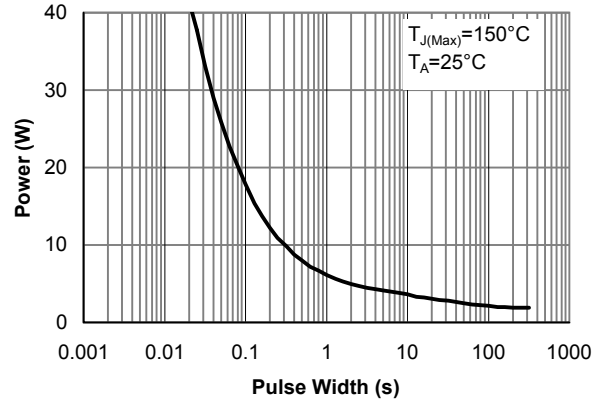


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

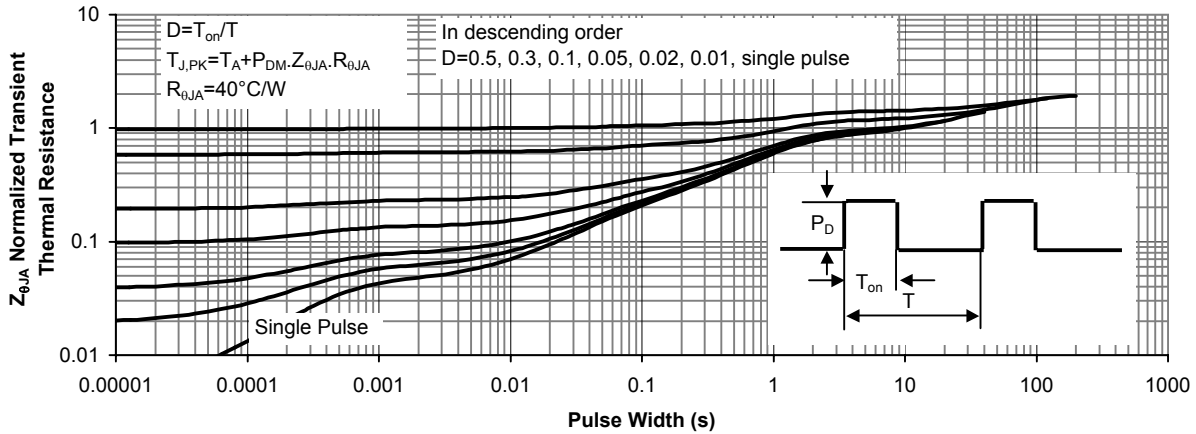


Figure 11: Normalized Maximum Transient Thermal Impedance

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: SCHOTTKY

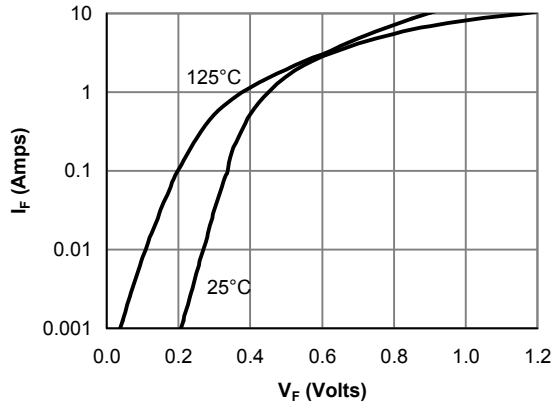


Figure 12: Schottky Forward Characteristics

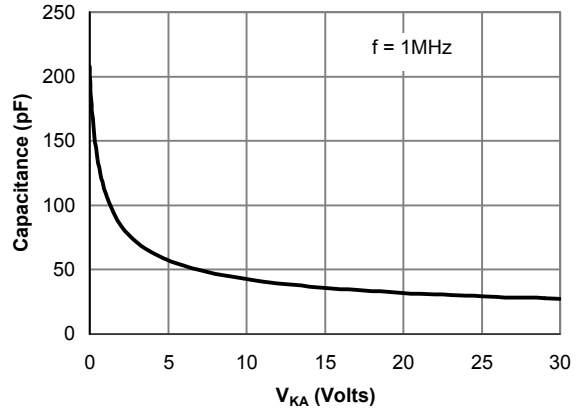


Figure 13: Schottky Capacitance Characteristics

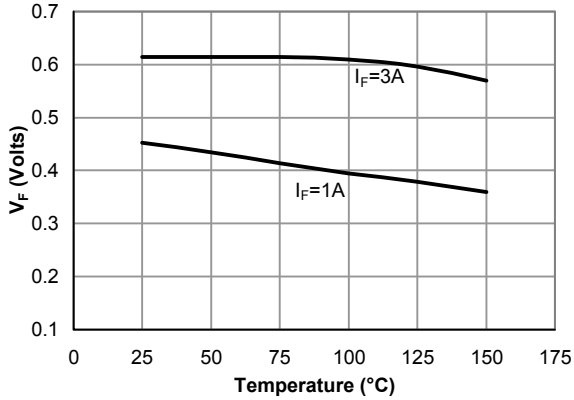


Figure 14: Schottky Forward Drop vs. Junction Temperature

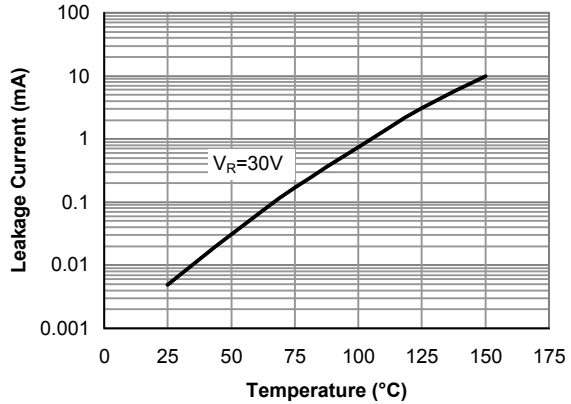


Figure 15: Schottky Leakage current vs. Junction Temperature

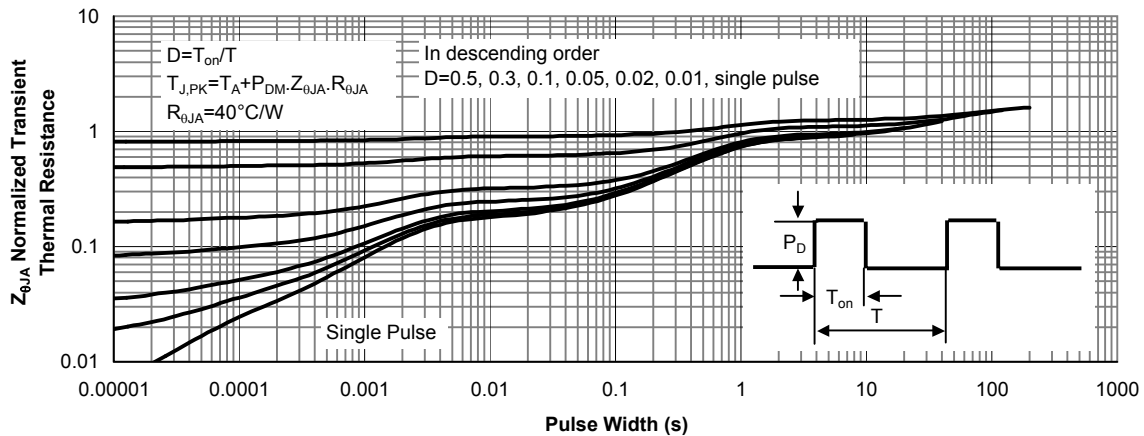


Figure 15: Schottky Normalized Maximum Transient Thermal Impedance